



## Material Content Data Sheet



<b>Sales Product Name</b>		IPB160N04S2-03		<b>Issued</b>		25. January 2018		
<b>MA#</b>		MA001036132						
<b>Package</b>		PG-TO263-7-3		<b>Weight*</b>		1528.29 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	12.294	0.80	0.80	8044	8044
leadframe	non noble metal	iron	7439-89-6	0.803	0.05		525	
	inorganic material	phosphorus	7723-14-0	0.241	0.02		158	
	non noble metal	copper	7440-50-8	801.714	52.45	52.52	524581	525265
wire	non noble metal	aluminium	7429-90-5	7.906	0.52	0.52	5173	5173
encapsulation	organic material	carbon black	1333-86-4	8.681	0.57		5680	
	plastics	epoxy resin	-	95.486	6.25		62479	
	inorganic material	silicondioxide	60676-86-0	474.536	31.05	37.87	310501	378660
leadfinish	non noble metal	tin	7440-31-5	12.317	0.81	0.81	8059	8059
plating	non noble metal	nickel	7440-02-0	0.269	0.02		176	
	inorganic material	phosphorus	7723-14-0	0.001	0.00	0.02	1	176
solder	noble metal	silver	7440-22-4	0.192	0.01		126	
	non noble metal	tin	7440-31-5	0.154	0.01		101	
	non noble metal	lead	7439-92-1	7.350	0.48	0.50	4809	5036
heatspreader	non noble metal	iron	7439-89-6	0.106	0.01		70	
	inorganic material	phosphorus	7723-14-0	0.032	0.00		21	
	non noble metal	copper	7440-50-8	106.210	6.95	6.96	69496	69587
*deviation	< 10%				Sum in total:	100.00		1000000

### Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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